

Product Name: ZX050C-WLB0808 (X1-WLB0808-4 U-WLB0808-4) Characterization testing bringup breakout module

Product Description: High Speed characterization module meeting 10GHz signal bandwidth with < 0.3dB insertion loss. Each pin of the device under test, U1, is accessible via 2 dedicated SMA connectors for external stimulus as well as measurement purpose.

ZX050C-WLB0808 is designed for ASIC (IC) characterization, functional testing of WLB0808-4 packaged device. ZX050C-WLB0808 is designed with 50 Ω (Ohms) trace impedance using 4 layer PCB. The module includes 35μ gold plated SMA connectors.

Ideal evaluation, bringup, and testing of any discrete component such as ESD diode, sensor, or any IC using WLB0808-4 footprint package.

Available SS1, SS2, SS3, SS4 0402 SMD landing pads – as default shorted to GND. User may cut the trace for dedicated I/O configuration of the pin.

Available GND test point header pin interfacing with the module's GND plane & GND fills

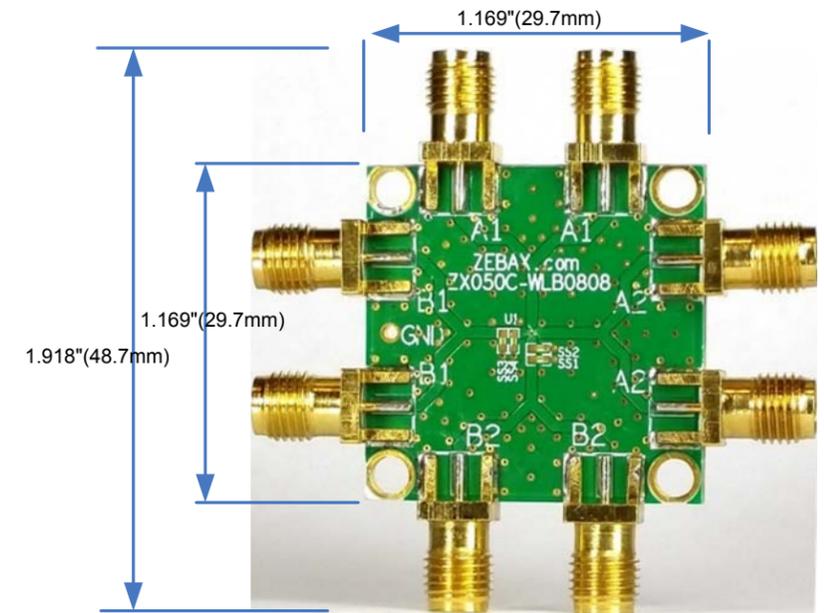
Application: Bringup, Characterization, testing, development, modular design evaluations

Target DUT : Designed specifically for any WLB0808-4 (X1-WLB0808-4 U-WLB0808-4) SMD device with SMA connectors accessing all pins of the WLB0808

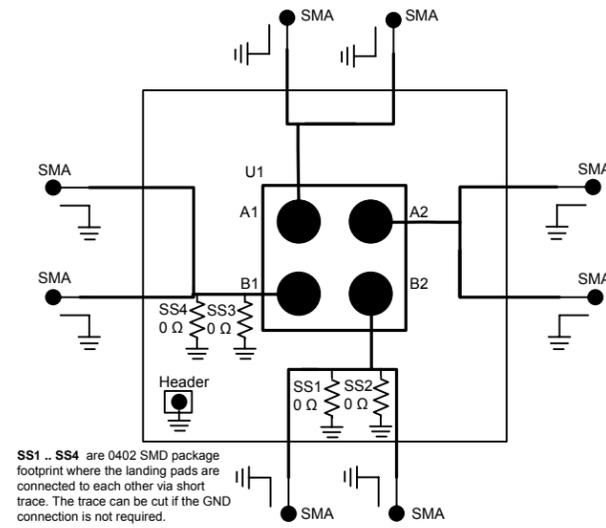
Pitch: Standard WLB08080 (X1-WLB0808-4 U-WLB0808-4) SMD package or equivalent

Headers: Ground access test point (GND) - 0.025" SQ with 0.32" (5.6mm) post height

DUT landing pads: Surface Mount, 4 pin package – WLB0808-4 (X1-WLB0808-4, U-WLB0808-4) or equivalent

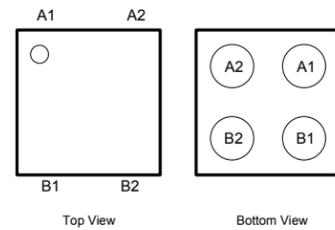


Simplified Block Diagram:



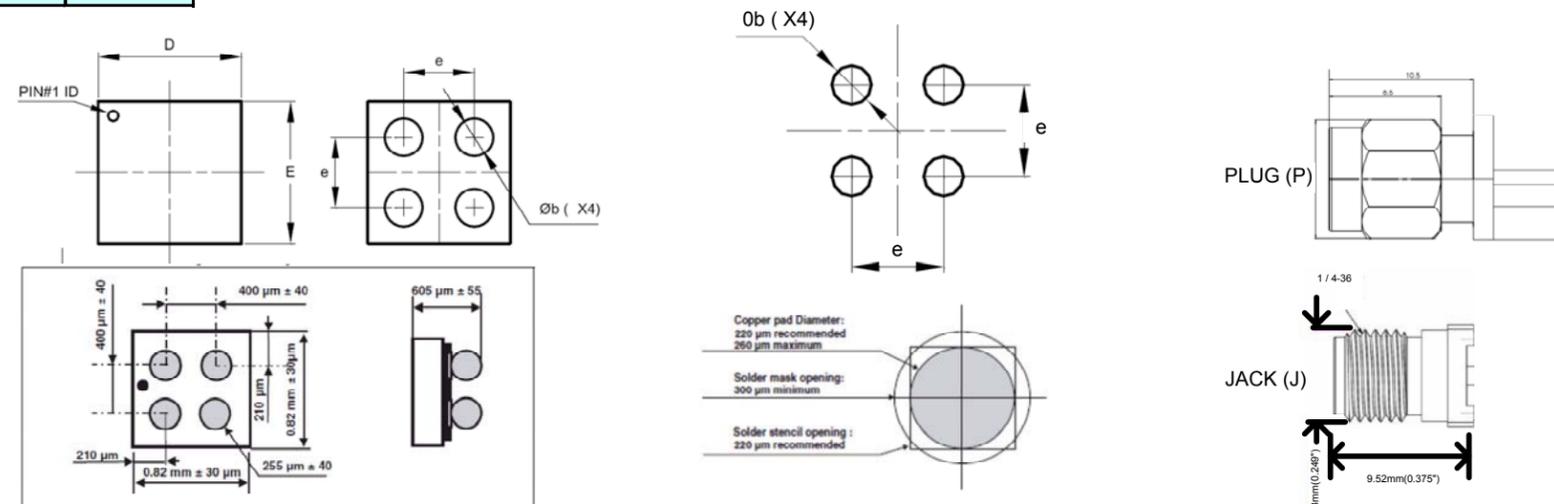
WLB0808 DIMENTIONS (mm)

UNIT		b	e	E
mm	max	0.255	0.40	0.795
	Typical	0.220	0.40	0.810
mm	min	0.215	0.40	0.795



OUTLINE Version	REFERENCES		
	IEC	JEDEC	JEITA
X1-WLB0808-4			
U-WLB0808-4			

Pad Layout



SMA:
 Impedance: 50Ω
 Temp Range: -65°C +165°C
 Vibration: MIL-STD-202, Method 213
 Frequency Range: DC – 12GHz
 Working Voltage: 335V max
 Withstand Voltage: 1000V rms
 Center Contact: ≤3mΩ
 Outer Contact: ≤2mΩ
 Insulation resistance: ≥5000MΩ
 VSWR Straight: ≤1.15 (0.8-2.5G)

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Ordering INFO:

Part Number
 ZX050C-WLB0808J SMA Jack Connector type (standard)
 ZX050C-WLB0808P SMA Plug connector type

NOTE: ZX050C-WLB0808 is shipped without DUT. All SMA connectors are installed.

Note
 ALL ZEBAX products are RoHS compliant and Lead Free unless otherwise indicated.

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SPECIFIED DIMENSIONS ARE INCHES (MM). ROHS COMPLIANT	ASSEMBLY DRAWING
ITEM: ZX050C-WLB0808	
DESCRIPTION: WLB0808 (X1-WLB0808-4 U-WLB0808-4) characterization testing bringup breakout adapter SMA	
CHECKED: M. MARINA	DRAWN: SLAVIK
REVISION: 1.0	
SHEET: 1 OF 1	